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Sputtered Al-N codoped p-type transparent ZnO thin films suitable for optoelectronic devices

Trilok Kumar Pathak^{a,*}, Vinod Kumar^{a,b}, L.P. Purohit^{a,b}

^aDepartment of Physics, University of Jammu, Jammu, India
^bDepartment of Physics, University of the Free State, Bloemfontein, South Africa

ABSTRACT

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Aluminum-doped (Al-N) codoped zinc oxide (ZnO) thin films were grown on glass substrate by radio frequency (RF) reactive magnetron sputtering using aluminum doped zinc oxide (AZO, 3.5 wt% Al₂O₃) target and N₂ as reactive gas. The structural, morphological and electrical properties were investigated with various flow rate of N₂ gas. X-ray diffraction results shows that sputtered ZnO thin films have wurtzite structure like sputtered ZnO film. Al-N thin films show high transparency (80% in visible region) at the substrate flow rate increases the transparency and band gap decreases. The band gap decreases with a variation of 0.54 eV and 0.2 eV for Al₂O₃ = 10⁻² and 10⁻¹ at room temperature, respectively. Current-voltage (I-V) characteristics of p-type codoped ZnO thin films are also discussed.

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1. Introduction

ZnO is a direct bandgap semiconductor [1]. ZnO is suitable material for the development of UV, optoelectronics devices and short wavelength light emitting diodes due to its large band gap (3.37 eV) and high exciton binding energy (60 meV) [2,3]. ZnO is natural-type semiconductor and the low stability of the deposit [4]. To realize the light emitting devices, an important issue is the fabrication of p-type ZnO with a high hole concentration and low resistance. It is very difficult to obtain p-type ZnO due to its self-compensated effect of native n-type carrier with deep level, low acceptor level and the low solubility of the acceptor dopants [5]. In spite of these difficulties, attempts in the past decades for p-type ZnO have various efforts to realize this goal have been attempted. [6,7]. Yamashita et al. proposed a donor-acceptor co-doping method, the donor and Al-Ga in with N being an acceptor [7]. Recently several co-doping techniques have been reported to prepare p-type ZnO film, such as co-doping of nitrogen (N) and gallium (Ga) [8], nitrogen (N) and beryllium (Be) [9], N and magnesium (Mg) [10] and Al and aluminum (Al) [11]. Among these co-doping techniques, N, Mg and Al because N, Al and Be-O bonds are stronger for N, Al and Be are easiest to sputter which were used to synthesize p-type ZnO thin films such as thermal vapor deposition (TVD) [12], pulsed laser

deposition (PLD) [14], RF magnetron sputtering [15] and sol-gel technique [16]. Among these techniques RF magnetron sputtering is best technique to obtain p-type conductivity with high carrier concentration and mobility [17–19]. A few literatures are available on co-doping method produced p-type nitrogen doped ZnO film by the Al-N co-doping method using RF magnetron sputtering with a N₂ sputtering gas using ZnAl sputtering target. The low resistive p-type codoped ZnO thin films have most applications in light emitting devices, transparent photo-voltaic devices and optoelectronic devices. These films can be used in the fabrication of transparent p-n junction that is fundamental structure of these optoelectronic devices.

In this paper, we have deposited low resistive p-type Al-N codoped ZnO thin films by RF sputtering using AZO (3.5 wt% Al) target. Effect of N₂ flow rate on structural, optical and electrical properties of Al-N codoped sputtered ZnO thin films are also investigated at room temperature.

2. Experimental details

ZnO powder (high chemical, 99.999% purity) and Al₂O₃ powder (Quintaris, 99.999% purity) were used to form target of sputtering. 23 g of AZO (2.0–2.5 wt% Al₂O₃) powder were taken in disc and compact it with pressure 10 ton using palletting machine to formed ceramic target with 2.5" diameter. The prepared target were sintered at 450 °C for 5 h after sintered the target (Fig. 1) is ready to use in RF sputtering coating unit (plasma magnetron

* Corresponding author. Tel.: +91 9876732344. E-mail: tkpathak@ujs.ac.in or tkp@ujs.ac.in